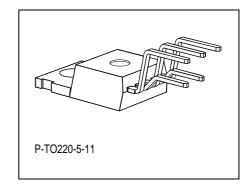
5-V Low Drop Voltage Regulator

TLE 4290

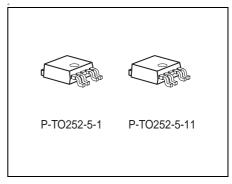
Features

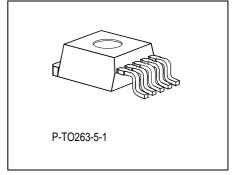
- Output voltage 5 V ± 2%
- Very low current consumption
- 450 mA current capability
- Power Good Feature
- Very low-drop voltage
- Short-circuit-proof
- Reverse polarity proof
- Suitable for use in automotive electronics



Functional Description

The TLE 4290 is a monolithic integrated low drop voltage regulator which can supply loads up to 450 mA with power good feature. An input voltage up to 42 V is regulated to $V_{\rm Q,nom} = 5.0$ V. The device is designed to supply μ -controllers in the severe environment of automotive applications. Therefore it is protected against overload, short circuit and over temperature conditions. Of course the TLE 4290 can been used also in all other applications, where a stabilized 5 V voltage is required.





Туре	Ordering Code	Package
TLE 4290	Q67000-A9407	P-TO220-5-11
TLE 4290 D	Q67006-A9408	P-TO252-5-1, P-TO252-5-11
TLE 4290 G	Q67006-A9405	P-TO263-5-1



Power Good

The Power Good PG pin informs e.g. the microcontroller in case the output voltage has fallen below the lower threshold $V_{\rm Q,pgt-d}$ of typ. 3.65 V. Connecting the regulator to a battery voltage at first the power good signal remains LOW. When the output voltage has reached the higher threshold $V_{\rm Q,pgt-i}$ the power good output remains still LOW for the power good delay time $t_{\rm rd}$. Afterwards the power good output turns HIGH. The delay time can be set by the user with an external capacitor at pin D according to the requirements of the application.

The Power Good circuitry supervises the output voltage. In case $V_{\rm Q}$ falls below the lower Power Good switching threshold $V_{\rm Q,pgt-d}$ the PG output is set LOW after the Power Good reaction time. The Power Good LOW signal is generated down to an output voltage $V_{\rm Q}$ to 1 V. A LOW signal at the Power Good pin informs that the battery was lost and memory is no longer valid.

The feature should be used in combination with a microcontroller with internal reset.

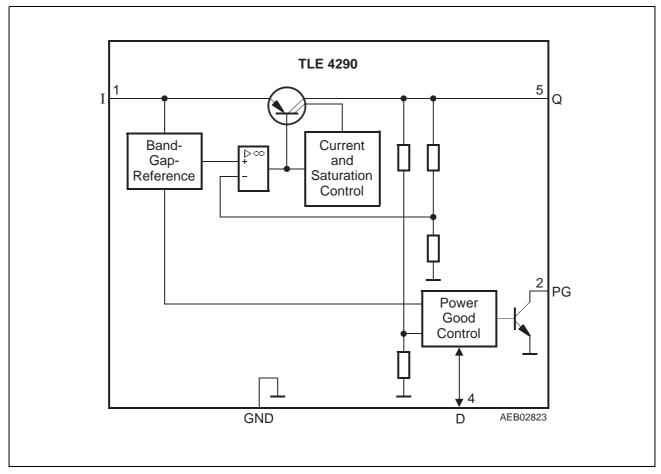


Figure 1 Block Diagram



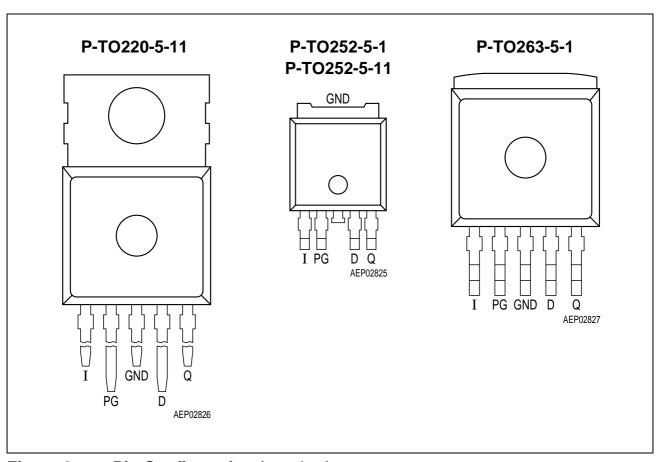


Figure 2 Pin Configuration (top view)

Table 1 Pin Definitions and Functions

Pin No.	Symbol	Function
1	1	Input; block to ground directly at the IC with a ceramic capacitor.
2	PG	Power Good ; open collector output. Add a pull-up resistor of > 5 k Ω to pin Q.
3	GND	Ground; Pin 3 internally connected to heatsink.
4	D	Delay ; connect a capacitor to GND for setting power good delay time.
5	Q	Output; block to ground with a capacitor, $C \ge 22~\mu\text{F}$ ESR < 5 Ω at 10 kHz.



 Table 2
 Absolute Maximum Ratings

Parameter	Symbol	Lim	it Values	Unit	Test Condition
		Min.	Max.		
Input I	-		1	1	
Voltage	V_{l}	-42	45	V	_
Current	I_{l}	_	_	_	Internally limited
Output Q					
Voltage	V_{Q}	-1.0	16	V	_
Current	I_{Q}	_	_	_	Internally limited
Power Good Output Po	}				
Voltage	V_{PG}	-0.3	25	V	_
Current	I_{PG}	-5	5	mA	_
Delay D					
Voltage	V_{D}	-0.3	7	V	_
Current	I_{D}	-2	2	mA	_
Temperature	•	•		•	•
Junction temperature	T_{j}	-40	150	°C	_
Storage temperature	T_{stg}	-50	150	°C	_

Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Table 3 Operating Range

Parameter	Symbol	Limi	t Values	Unit	Remarks
		Min.	Max.		
Input voltage	V_{I}	5.5	42	V	_
Junction temperature	T_{j}	-40	150	°C	-
Thermal Resistance			•	•	•
Junction case	R_{thj-c}	_	4	K/W	_
Junction ambient	$R_{\text{thj-a}}$	_	53	K/W	TO263 ¹⁾
Junction ambient	$R_{\text{thj-a}}$	_	78	K/W	TO252 ¹⁾
Junction ambient	$R_{\text{thj-a}}$	_	65	K/W	TO220

¹⁾ Worst case, regarding peak temperature; zero airflow; mounted on a PCB FR4, $80 \times 80 \times 1.5 \text{ mm}^3$, heat sink area 300 mm²

Note: In the operating range, the functions given in the circuit description are fulfilled.



Table 4 Characteristics

 $V_{\rm I}$ = 13.5 V; -40 $^{\circ}{\rm C}$ < $T_{\rm j}$ < 150 $^{\circ}{\rm C}$ (unless otherwise specified)

Parameter	Symbol	Limit Values			Unit	Measuring
		Min.	Тур.	Max.		Condition
Output			1	•	1	
Output voltage	V_{Q}	4.9	5.0	5.1	V	$\begin{array}{c} \text{5 mA} < I_{\text{Q}} < 400 \text{ mA}; \\ \text{6 V} < V_{\text{I}} < 28 \text{ V} \end{array}$
Output voltage	V_{Q}	4.9	5.0	5.1	V	$5 \text{ mA} < I_{\text{Q}} < 200 \text{ mA};$ $6 \text{ V} < V_{\text{I}} < 40 \text{ V}$
Output current limitation	I_{Q}	450	700	_	mA	1)
Current consumption; $I_{q} = I_{l} - I_{Q}$	I_{q}	_	200	230	μА	$I_{\rm Q}$ = 1 mA; $T_{\rm j}$ = 25 °C
Current consumption; $I_q = I_l - I_Q$	I_{q}	_	200	255	μА	$I_{\rm Q}$ = 1 mA; $T_{\rm j}$ \leq 85 °C
Current consumption; $I_q = I_l - I_Q$	I_{q}	_	5	12	mA	$I_{\rm Q}$ = 250 mA
Current consumption; $I_{q} = I_{l} - I_{Q}$	I_{q}	_	12	25	mA	I _Q = 400 mA
Drop voltage	V_{dr}	_	250	500	mV	$I_{\rm Q}$ = 300 mA $V_{\rm dr}$ = $V_{\rm I}$ - $V_{\rm Q}^{-1)}$
Load regulation	$\Delta V_{Q,lo}$	-30	15	30	mV	$V_{\rm I}$ = 6 V; $I_{\rm Q}$ = 5 mA to 400 mA
Line regulation	$\Delta V_{Q,li}$	-15	5	15	mV	$V_{\rm I}$ = 8 V to 32 V; $I_{\rm Q}$ = 5 mA
Power supply ripple rejection	PSRR	_	60	_	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp
Temperature output voltage drift	$\mathrm{d}V_{\mathrm{Q}}/\mathrm{d}T$	_	0.5	_	mV/K	_
Output Capacitor	C_{Q}	22	_	_	μF	ESR < 5 Ω in the operation range
Power Good Output PG	and Delay	Timin	g D		II.	,
Power Good switching threshold	$V_{Q,pgt-i}$	4.45	4.65	4.80	V	$V_{ m Q}$ increasing
Power Good switching threshold	$V_{ m Q,pgt-d}$	3.50	3.65	3.80	V	$V_{ m Q}$ decreasing



Table 4 Characteristics (cont'd)

 $V_{\rm I}$ = 13.5 V; -40 °C < $T_{\rm i}$ < 150 °C (unless otherwise specified)

Parameter	Symbol Limit Values			ues	Unit	Measuring
		Min.	Тур.	Max.		Condition
Power Good output low voltage	V_{PGL}	_	0.2	0.4	V	$R_{\rm PG} \geq 5 \ {\rm k}\Omega;$ $V_{\rm Q} > 1 \ {\rm V}$
Power Good output leakage current	I_{PGH}	_	0	2	μΑ	V _{PG} > 4.5 V
Power Good charging current	$I_{D,c}$	3	6	9	μΑ	V _D = 1 V
Upper timing threshold	V_{DU}	1.5	1.8	2.2	V	_
Lower timing threshold	V_{DL}	0.60	0.85	1.10	V	_
Power Good delay time	$t_{\sf rd}$	10	16	22	ms	$C_{\rm D}$ = 47 nF
Power Good reaction time	$t_{\rm rr}$	0.2	0.5	2.0	μS	$C_{\rm D} = 47 \; {\rm nF}$

¹⁾ Measured when the output voltage $V_{\rm Q}$ has dropped 100 mV from the nominal value obtained at $V_{\rm I}$ = 13.5 V.

Note: The listed characteristics are ensured over the operating range of the integrated circuit. Typical characteristics specify mean values expected over the production spread. If not otherwise specified, typical characteristics apply at T_a = 25 °C and the given supply voltage.

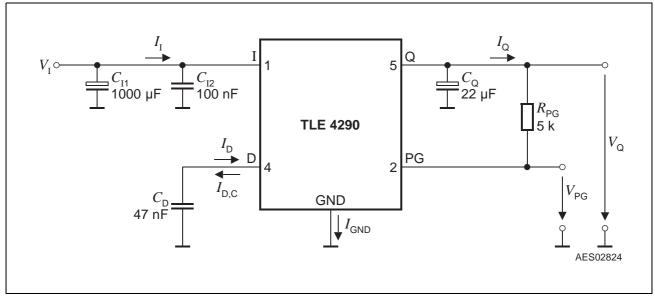


Figure 3 Test Circuit



Application Information

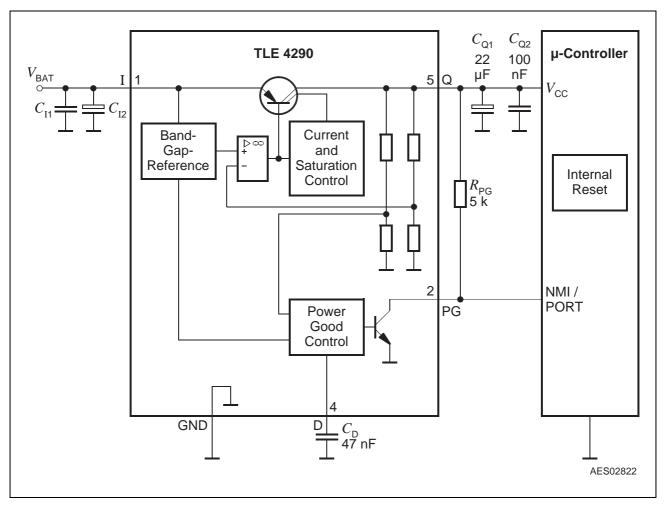


Figure 4 Application Diagram

Input, Output

An input capacitor is necessary for damping line influences. A resistor of approx. 1 Ω in series with C_1 , can damp the LC of the input inductivity and the input capacitor.

The TLE 4290 requires an output capacitor of at least 22 μ F with an ESR below 5 Ω for stability.

Power Good

The Power Good pin informs e.g. the micro-controller in case the output voltage has fallen below a threshold of typ. 3.65 V. When the battery voltage is supplied the Power Good signal indicates a loss of memory due to missing power. After the Memory Good switching threshold is reached the Power Good output remains low for the Power Good delay time. This time can be set by the user with an external capacitor at pin D according to the requirements of the application, e.g. the time until the microcontroller is initialized and ready to receive any information.



The power good circuit supervises the output voltage. In case $V_{\rm Q}$ falls below the Power Good switching threshold the Power Good output PG is set LOW after the power good reaction time. The power good LOW signal is generated down to an output voltage $V_{\rm Q}$ to 1 V. A LOW signal at the power good pin informs that the battery was lost and memory is no longer valid.

The feature should only be used in combination to a microcontroller with internal reset.

For the power good delay time after the output voltage of the regulator is above the reset threshold, the reset signal is set High again. The reset delay time is defined by the reset delay capacitor $C_{\rm D}$ at pin D.

The Power Good delay time is defined by the charging time of an external delay capacitor $C_{\rm D}$.

$$C_{\rm D} = (t_{\rm rd} \times I_{\rm D,c}) / \Delta V \tag{1}$$

With:

- C_D = Power Good delay capacitor
- t_{rd} = Power Good delay time
- $\Delta V = V_{DU}$, typical 1.8 V
- I_{D.c} = Charge current typical 6 μA

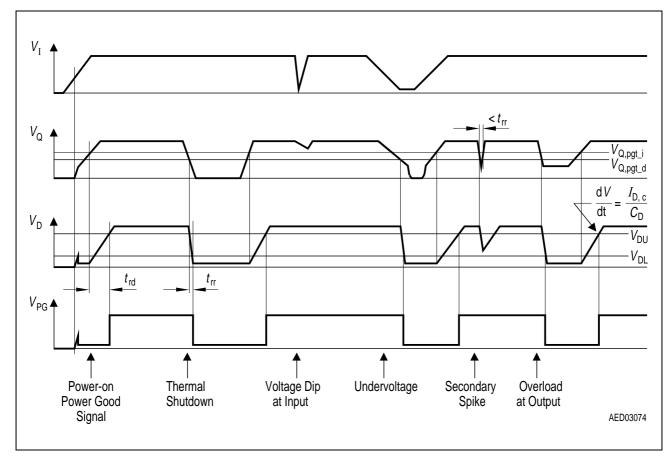


Figure 5 Power Good Timing



The power good reaction time $t_{\rm rr}$ is the time it takes the voltage regulator to set power good output PG LOW after the output voltage has dropped below the power good switching threshold. It is typically 0.5 μ s for delay capacitor of 47 nF. For other values for $C_{\rm D}$ the reaction time can be estimated using the following equation:

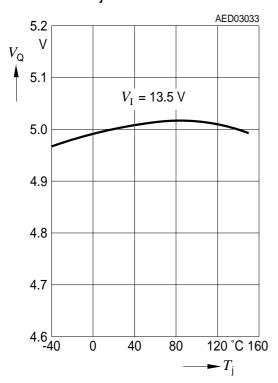
$$t_{\rm rr} = 10 \text{ ns/nF} \times C_{\rm D} \tag{2}$$

The Power Good output is an open collector output. It requires externally a pull-up resistor of at least 5 k Ω to Q.

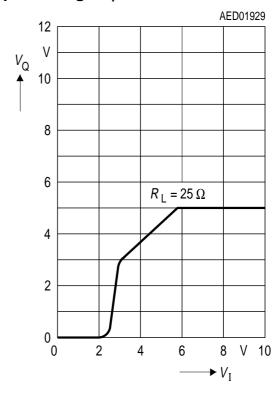


Typical Performance Characteristics

Output Voltage $V_{\rm Q}$ versus Temperature $T_{\rm j}$

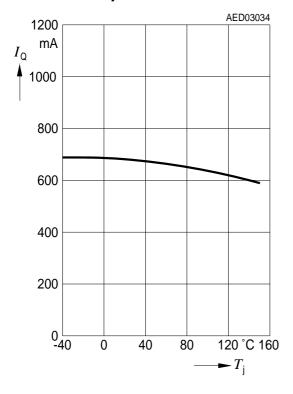


Output Voltage $V_{\rm Q}$ versus Input Voltage $V_{\rm I}$

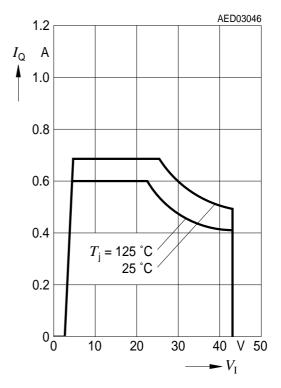




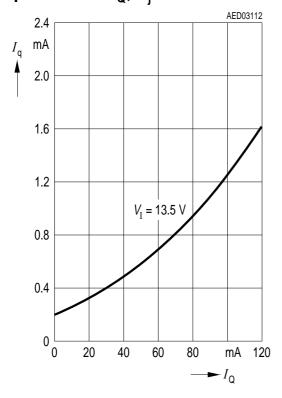
Output Current I_{Q} versus Temperature T_{i}



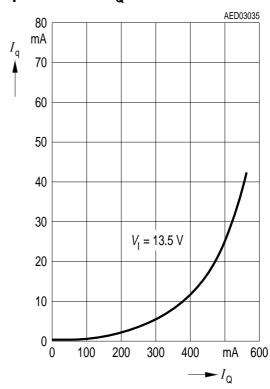
Output Current $I_{\rm Q}$ versus Input Voltage $V_{\rm I}$



Current Consumption I_q versus Output Current I_Q ; T_j = 25 °C

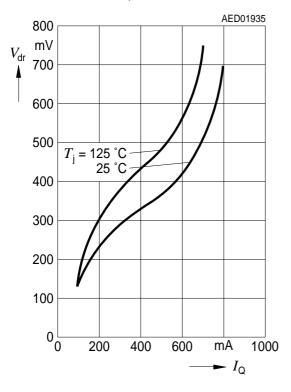


Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm Q}$

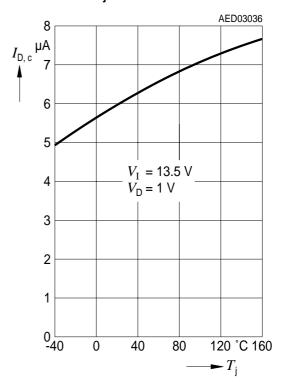




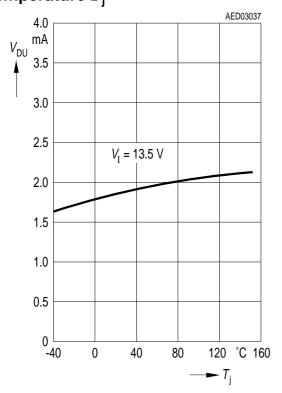
Drop Voltage V_{dr} versus Output Current I_{Q}



Charge Current $I_{D,c}$ versus Temperature T_i



Upper Timing Threshold V_{DU} versus Temperature T_{i}





Package Outlines

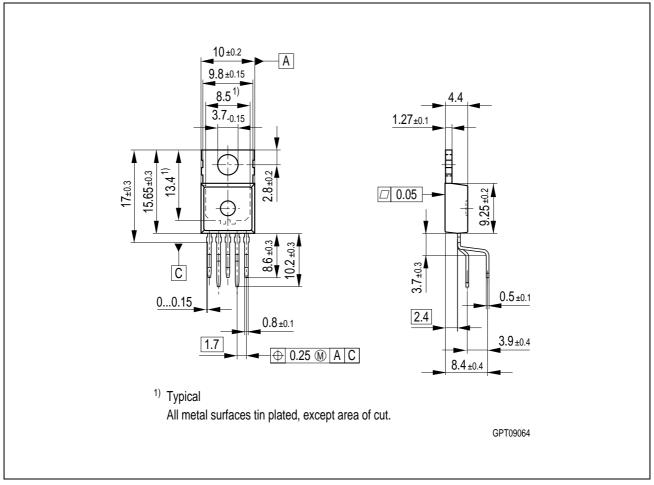


Figure 6 P-TO220-5-11 (Plastic Transistor Single Outline)

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SMD = Surface Mounted Device



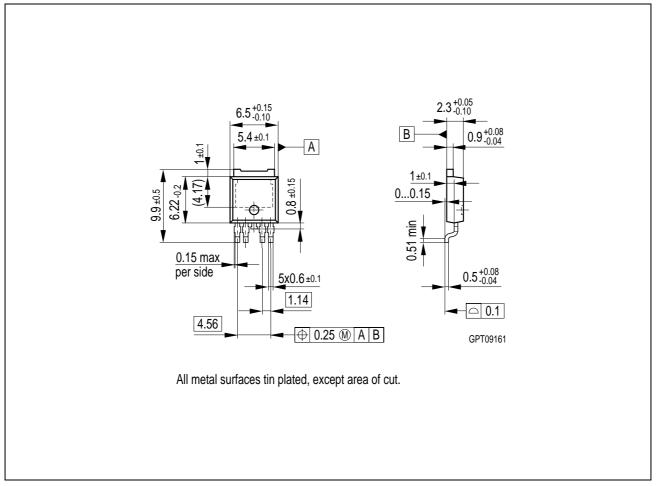


Figure 7 P-TO252-5-1 (Plastic Transistor Single Outline)

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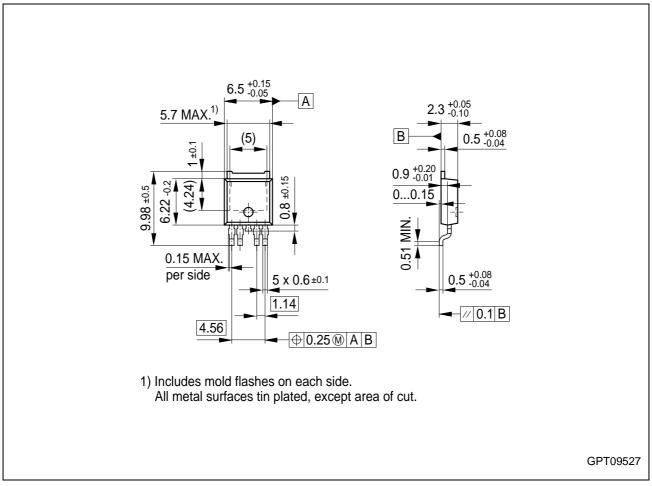


Figure 8 P-TO252-5-11 (Plastic Transistor Single Outline)

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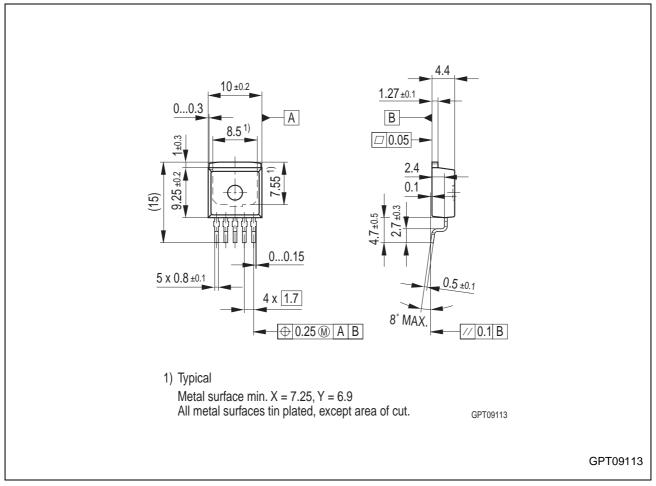


Figure 9 P-TO263-5-1 (Plastic Transistor Single Outline)

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Remarks

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